

ABSTRACT

The present invention relates to: a polishing pad including a polishing layer having a circular polishing surface, the polishing layer having one or more grooves α that each have a first end $E\alpha 1$ and a second end $E\alpha 2$ which is closer to the outer circumference of the polishing surface than the first end $E\alpha 1$ is and that each extend from the first end $E\alpha 1$ toward the second end $E\alpha 2$, the first end $E\alpha 1$ of each groove α being present in an area (1) that is a range of 70.0 to 99.0% relative to the radius of the polishing surface from the center of the polishing surface, the second end $E\alpha 2$ of each groove α being not connected to the outer circumference of the polishing layer; and a polishing method in which the polishing pad is used.